Transistors

2SC6036

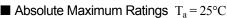
Silicon NPN epitaxial planar type

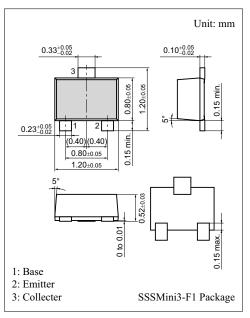
For general amplification Complementary to 2SA2162

Features

- \bullet Low collector-emitter saturation voltage $V_{CE(sat)}$
- SSS-Mini type package, allowing downsizing of the equipment and automatic insertion through the tape packing

Absolute Maximum Ratings $T_a = 25^{\circ}C$							
Parameter	Symbol	Rating	Unit				
Collector-base voltage (Emitter open)	V _{CBO}	15	V				
Collector-emitter voltage (Base open)	V _{CEO}	12	V				
Emitter-base voltage (Collector open)	V _{EBO}	5	V				
Collector current	I _C	500	mA				
Peak collector current	I _{CP}	1	A				
Collector power dissipation	P _C	100	mW				
Junction temperature	Tj	125	°C				
Storage temperature	T _{stg}	-55 to +125	°C				





Marking Symbol : 4U

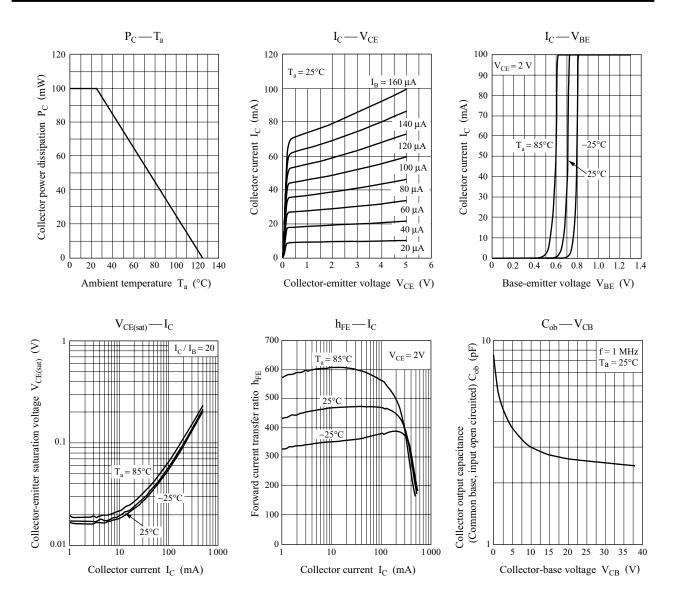
Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Collector-base voltage (Emitter open)	V _{CBO}	$I_{\rm C} = 10 \ \mu {\rm A}, I_{\rm E} = 0$	15			V
Collector-emitter voltage (Base open)	V _{CEO}	$I_{\rm C} = 1 {\rm mA}, I_{\rm B} = 0$	12			V
Emitter-base voltage (Collector open)	V _{EBO}	$I_{\rm E} = 10 \ \mu A, I_{\rm C} = 0$	5			V
Collector-base cutoff current (Emitter open)	I _{CBO}	$V_{CB} = 10 \text{ V}, I_E = 0$			0.1	μΑ
Forward current transfer ratio	h _{FE}	$V_{CE} = 2 V, I_C = 10 mA$	270		680	
Collector-emitter saturation voltage	V _{CE(sat)}	$I_{\rm C} = 200 \text{ mA}, I_{\rm B} = 10 \text{ mA}$			250	mV
Transition frequency	\mathbf{f}_{T}	$V_{CB} = 2 V, I_E = -10 mA, f = 200 MHz$		200		MHz
Collector output capacitance (Common base, input open circuited)	C _{ob}	$V_{CB} = 10 \text{ V}, f = 1 \text{ MHz}$		4.5		pF

Note) Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7030 measuring methods for transistors.

2SC6036

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